

Bench-top / Batch Reflow Oven

BT301N

Dynamic Thermal Profile using Nitrogen Batch Reflow Oven with Android™ Operating System

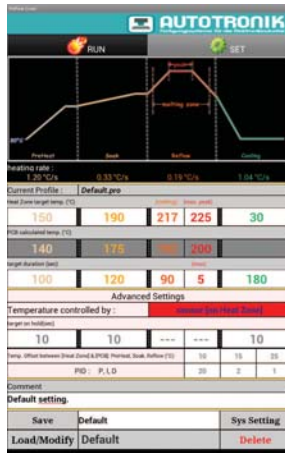
Match your thermal process specifications for preheat, soak, reflow, and cooling on the first PCB you produce with by using revolutionary new BT301 Batch Reflow Oven. Having the thermal conditions of an inline reflow system in a bench-top unit with a full dynamic thermal process.



The use of nitrogen for lead-free assembly in the reflow process improves solder joint strength and reduces oxidation. The BT301N is ideal for product development, prototyping, and small series production. Solder profiles are easily set-up and stored through the control app of the BT301N's exclusive hardware control and Android operating system. The dynamic control system takes care of size and complexity of your assembly and makes it a closed loop process, something only large and costly thermal systems can normally offer.

Features

- ⊙ Real time close loop PID temperature control for leadfree profile
- ⊙ Quick Smart programming by rising rate control (degree change per second)
- ⊙ Infrared and forced convection combine for efficient lead-free reflow
- ⊙ Nitrogen gas flow control produces better solder joint and reduces oxidation
- ⊙ Real time temperature profile display
- ⊙ Android system on multi-core CPU platform
- ⊙ 7" touch screen high resolution LCD display
- ⊙ Compact design ideal for labs, schools, prototyping and low-volume job shops
- ⊙ WiFi temperature profile printing and data storage
- ⊙ Rosin filter in nitrogen circulator



Real-Time dynamic thermal Control via On-Board measuring device

The BT301N has an advanced setting in which you can turn on the real time dynamic process. The unit can then via real-time feedback from the measuring system which is attached at a strategic location on the PCB surface.

The heater control and fan speed is based on the actual temperature measured on the product. The target temperature is equal to the dynamic measuring system temperature and there is no offset, making this a perfect tool for prototyping and small series.

Specification

Machine Model

Applicable solder types
PCB holding size
PCB effective heating area
Heating method
Temperature range
Temperature control method

Warm-up time
Computer control
Display panel
Temperature control setting

Temperature profile display
Temp profile printing
Auto chamber
Storage
Electrical
Power
Nitrogen pressure
Nitrogen flow rate
Dimensions
Weight

BT301N

Lead-Free and Leaded
350 mm x 240 mm
250 mm x 200 mm
Quartz IR & Forced Hot Air Convection
Ambient - 310 °C
Real time close loop PID temperature control for lead free profile
approx. 2 min.
Build-in dual core CPU on board computer
7" touch screen high resolution LCD display
Quick smart profile programming by temperature rising rate control (degree change per second)
Real time temperature profile display
WiFi temperature profile printing
open / close
External data storage via WiFi connection
230 V, Single Phase, 50/60 Hz, 30A
3000W
0.3 MPa
0 - 150L/min
780 mm L x 560 mm W x 370 mm H
approx. 82 Kg

* We reserve the right to make changes without notice.